FSL Logo

PRE ALERT - DEVICE MIGRATION
Generic Copy

This notice is Freescale Confidential Proprietary and is only intended for the customer listed on this notification.

ISSUE DATE:	02-Apr-2015
NOTIFICATION:	P16724
TITLE:	Mitsui Assembly Site Closure and Package Migration Motor Drivers

DEVICE(S)

MPN
MPC17510EJ
MPC17510EJR2
MPC17511EV
MPC17511EVEL
MPC17529EV
MPC17529EVEL
MPC17531ATEV
MPC17531ATEVEL
MPC17533EV
MPC17533EVEL

This notice is Freescale Confidential Proprietary and is only intended for the customer listed on this notification.

AFFECTED CHANGE CATEGORIES

- ASSEMBLY PROCESS
- ASSEMBLY SITE
- PACKAGE CHANGE

DESCRIPTION OF CHANGE

Freescale Semiconductor received a Product Termination Notification from Mitsui High-Tec, Inc. regarding the closure of the Mitsui Kumanoto package assembly site. As a result of the Mitsui assembly site closure, Freescale Semiconductor announces the device migration of parts associated with three Mitsui package types that will no longer be available: VMFP16, VMFP20 and TSSOPW24. A total of four products will migrate from Mitsui to Amkor Philippines assembly site with JEDEC standard TSSOP packages, and one product will migrate from Mitsui to Freescale Tianjin assembly with QFN package. Final test will be performed at Freescale Tianjin Final Manufacturing (TJNFM) site, Tianjin China.

The new package migration impacts form and fit of the devices. Customers should evaluate the change details and begin planning for conversion based on the last order date and last ship date:
LAST BUY DATE: 30-Sep-2015
LAST SHIP DATE: 31-Mar-2016

Below table summarizes the migration details:

Current Part Number / Tape & Reel	Logical Part Name	Status	Current Package	Current Size LxWxH	New Migration Part Number / Tape & Reel	New Package	New Size LxWxH
MPC17510EJ /R2	NOUVEAU	Migrate	TSSOP24	7.9x7.6x1.2	MPC17510AEJ /R	TSSOP24	7.9x6.4x1.1
MPC17511EV /EL	PEONY VMFP	Migrate	MFP16 EIAJ-2	5.4x8.1x2.0	MPC17511EP /R	QFN24	4x4x1.2
MPC17529EV /EL	STD SMOS MPC17529	Migrate	MFP20 EIAJ-2	7.2x8.1x2.0	MPC17529EJ /R	TSSOP20	6.6x4.5x1.1
MPC17531ATEV /EL	GEMINI VMFP	Migrate	MFP20 EIAJ-2	7.2x8.1x2.0	MPC17531ATEJ /R	TSSOP20	6.6x4.5x1.1
MPC17533EV /EL	STD SMOS	Migrate	MFP16	5.4x8.1x2.0	MPC17529EJ /R	TSSOP20	6.6x4.5x1.1

	MPC17533		EIAJ-2				

REASON FOR CHANGE

Mitsui assembly plant closure - packages will no longer be offered.

ANTICIPATED IMPACT OF PRODUCT CHANGE(FORM, FIT, FUNCTION, OR RELIABILITY)

Change to Form and Fit (same number of leads, same pin-out, similar shape, but smaller). Function and Reliability are unchanged.

Freescale will consider specific conditions of acceptance of this change submitted within 30 days of receipt of this notice on a case by case basis. To request further data or inquire about the notification, please enter a Service Request.

For sample inquiries - please go to www.freescale.com

QUAL DATA AVAILABILITY DATE: 30-Nov-2015

QUALIFICATION STATUS: IN PROCESS

QUALIFICATION PLAN:

N/A

RELIABILITY DATA SUMMARY:

Available upon qualification completion.

ELECTRICAL CHARACTERISTIC SUMMARY:

Available upon qualification completion.

CHANGED PART IDENTIFICATION:

N/A

SAMPLE AVAILABILITY DATE: 15-Jun-2015

ATTACHMENT(S):

External attachment(s) FOR this notification can be viewed AT:
P16724_Case_Outline_Comparison_Mitsui_Package_Migration.pdf